



HPC SUPERCOMPUTING

Samtec's high-density, high-speed connectors are immediately available to handle signals in demanding high-performance and supercomputing applications. For unique design needs, Samtec can create custom interconnects that deliver the density and performance required. Customers can access our industry-leading signal integrity expertise as part of Samtec's commitment to Sudden Service®. For more information visit samtec.com/hpc-supercomputing or email SIG@samtec.com.

Product Features & Benefits

- Industry-leading cable performance
- Signal integrity-optimized solutions
- High bandwidth / low latency systems
- Extended signal reach
- Small form factors / ultra-high densities

Design & Development Support

- Industry-leading component and system-level engineering expertise
- Samtec cable assemblies also undergo cable flex and/or dynamic testing to prove consistent electrical stability in demanding applications
- Samtec works with system architects to optimize the architecture for cable management, keeping signal integrity and thermals in mind



SIGNAL INTEGRITY SUPPORT

Samtec is the industry leader in Signal Integrity. Our mission is to help you attain full system optimization - from Silicon-to-Silicon™.

- Full channel analysis
- System optimization recommendations
- PDN simulations
- Advanced product design support

Visit samtec.com/sig or contact SIG@samtec.com.

ENGINEERED CUSTOMS & EXPRESS MODIFICATIONS

Samtec offers custom and modified products with low or no NRE charges, quick turn samples, short lead times and low or no MOQs.

Choose any high-speed connector, breakout configuration and high-speed precision cable to create a solution for any specific application.

Contact HDR@samtec.com.

EVALUATION & DEVELOPMENT KITS

Samtec-designed kits simplify the interconnect design process and reduce time to market.

Kits are tested and verified by Samtec's signal integrity experts before customer delivery.

Visit samtec.com/kits or contact KitsAndBoards@samtec.com.

ONLINE TOOLS

Solutionator®: Quickly build mated connector sets or design full cable assemblies



samtec.com/cablebuilder



samtec.com/hsb2b-solutionator



samtec.com/discrete-cablebuilder

Picture Search: Browse through Samtec's most popular products to find the ideal solution

samtec.com/picturesearch

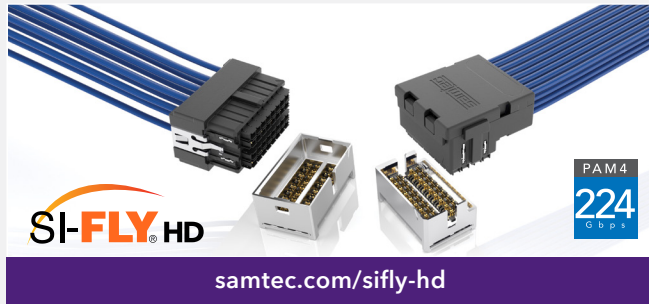
Downloadable Resources: Immediate and unlimited access to select the right solution - 3D models, prints and footprints, test reports, white papers and more

samtec.com

INTERCONNECT SOLUTIONS

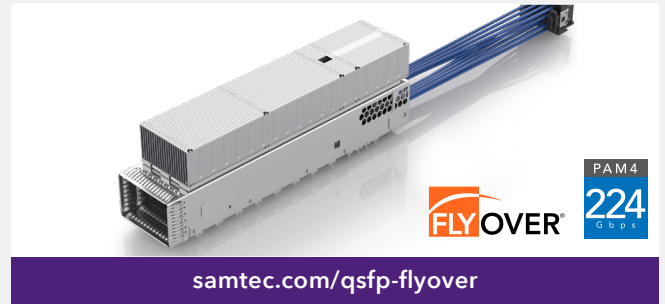
Si-Fly® HD

Si-Fly® HD co-packaged copper or optical (CPX) and near-chip systems provide the highest density 224 Gbps PAM4 solution in today's market with a path to 448 Gbps.



Flyover® SFP/QSFP/OSFP Systems

These direct attach Flyover® SFP/QSFP/OSFP cable assemblies route high-speed signals through Eye Speed® ultra low skew twinax cable for improved signal integrity.



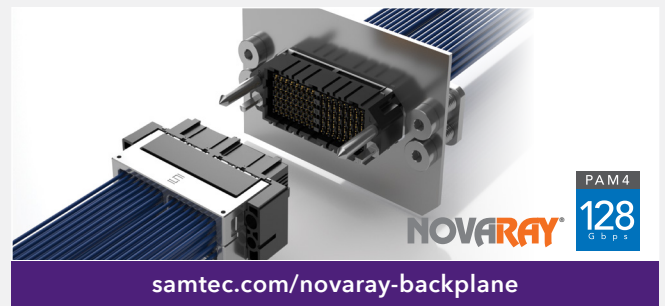
NovaRay® High-Density Connectors

NovaRay® combines extreme density and performance for 128 Gbps PAM4 per channel in 40% less space than traditional arrays.



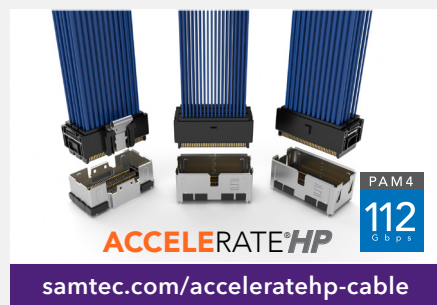
NovaRay® Backplane

NovaRay® Micro Rugged Backplane system combines ultra-high density with an offset footprint for optimal signal integrity performance to 128 Gbps PAM4.



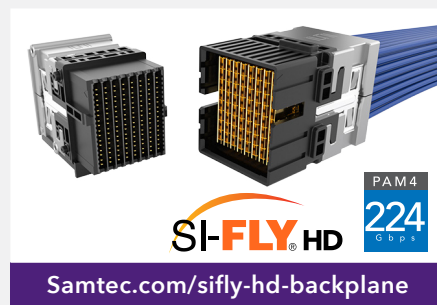
AccelRate® HP

High-performance cable-to-board system with differential pair, single-ended or mixed signaling configurations.



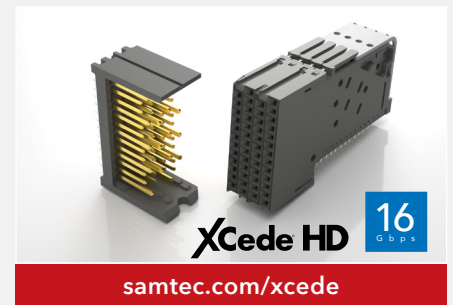
High-Density Backplane

The 224 Gbps PAM4 Si-Fly® HD backplane system offers up to 2,048 differential pairs in one open rack unit.



XCede® HD

High-Density backplane system features a small form factor ideal for density-critical applications.



XCede® is a registered trademark of Amphenol Corporation.

Visit [samtec.com](https://www.samtec.com) to view our full line of interconnect solutions.

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